Title: Datasheet for AM5726, AM5728  Customer Contact: PCN Manager Dept: Quality Services  Change Type:  Assembly Site Design Wafer Bump Site Wafer Bump Materials Assembly Materials Part number change Wafer Bump Materials Assembly Materials Part number change Wafer Bump Process Mechanical Specification Test Site Wafer Fab Materials Packing/Shipping/Labeling Test Process  Notification Details  Description of Change:  Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below.  The following change history provides further details.  PAM5728, AM5728, AM5726  SPRSSSIG-DECEMBER 2016-REVISED June 2017  Changes from November 28, 2016 to June 6, 2017 (from B Revision (November 2016) to C Revision)  Moved device hex code from TRN to DM. Changed PNC in Davice Comparison table to "Not Supported"  Updated column description parameter [4] in Ball Characteristics Table.  Updated column description parameter [4] in Ball Characteristics Table.  Added RO On-die Oscillator Clock section.  Added ROW DS Timing Specification Table 17-15 and Table 7-12.  Added New MANUAL3 and MANUAL4 timing mode options for DP11/273 in Table 7-2.  Added New MS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2021  Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2032  Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2033  Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2044  Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2054  Added New MST Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2055  Added New MST Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2056  PREMOVED TABLES TABLES TABLES TABLES TABLES TABLES TABLES TABLES TABLES	<b>PCN Number:</b> 20170728000	PCN Date:	Διιαι	ıst 18, 2017			
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Assembly Site   Design   Wafer Bump Site   Assembly Process   Data Sheet   Wafer Bump Material   Assembly Materials   Part number change   Wafer Bump Process   Wafer Bump Process   Materials   Parking/Shipping/Labeling   Test Site   Wafer Fab Process   Wafer Fa			DC	Quality .	Dei vices		
Assembly Process    Assembly Materials   Part number change   Wafer Bump Material		osian		Wafor Ruma Cit	÷0		
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Notification Details  Description of Change:  Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.  AM5728, AM5728  TEXAS INSTRUMENTS  TEXAS INSTRUMENTS  AM5728, AM5726  Changes from November 28, 2016 to June 6, 2017 (from B Revision (November 2016) to C Revision)  Page  Moved device hex code from TRM to DM.  Changed 'No' in Device Comparison table to 'Not Supported'  Updated column description parameter [4] in Ball Characteristics Table.  Updated column description parameter [4] in Ball Characteristics Table.  Changed GPMC 1 Load / 5 Load to Default Mode / Alternate Mode in Table 4-29  Added footnotes in Electrical Characteristics section califying VDDs in each table.  Added RC On-die Oscillator Clock section.  Added RC On-die Oscillator Clock section.  Added mem ARNUAL3 and MANUAL4 timing mode options for DPI1/2/3 in Table 7-2.  Added mem 3. dir ow into the Manual Function Mapping for VIP1 28 table.  Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation.  2036  Updated Virtual Mode Case Details for McASP2 in Table 7-50.  Updated Virtual Mode Case Details for McASP2 in Table 7-50.  Updated Virtual Mode Case Details for McASP2 in Table 7-64.  Updated Virtual Mode Case Details for McASP2 in Table 7-65.  Updated Hynologiagnams (parameters HS2006) and HS2006).  Removed McASP 'ahclks' signals from Table 7-63 and Table 7-64 to avoid confusion.  300  Updated Hynologiagnams (parameters HS2006) and HS2006).  Removed McASP 'ahclks' signals from Table 7-63 and Table 7-64 to avoid confusion.  301  Device Family  Change From:  Change From:  Change From:  Change To:  AM5728  SPRS953B  SPRS953C  These changes may be reviewed at the datasheet links provided.  http://www.ti.com/product/AM5726							
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Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.   ■ IEXAS AM5728, AM5726    INSTRUMENTS SPRSSSSC—DECEMBER 2015—REVISED JUNE 2017  Changes from November 28, 2016 to June 6, 2017 (from B Revision (November 2016) to C Revision) Page  • Moved device hex code from TRM to DM. • 6 • Changed "No" in Device Comparison table to "Not Supported" • 6 • Updated column description parameter [4] in Ball Characteristics Table. • 10 • Added a note to gome. a[22:19] and gome. a[27:24] signals about internal pulldowns activation • 121 • Changed GPMC 1 Load / 5 Load note of June 1 Load (Page 1) 150 • Added Rodnotes in Electrical Characteristics section clarifying VDDS in each table • 29 • Added Rodnotes in Electrical Characteristics section clarifying VDDS in each table • 20 • Added Rodnotes in Electrical Characteristics section Charyling VDDS in each table • 20 • Added Rodnotes in Electrical Characteristics section PDH1/2/3 in Table 7-2 • Added mmC3 dk row into the Manual Function Mapping for VIP1 28 table • 20 • Added Rodnotes in Electrical Translate of PDH1/2/3 in Table 7-2 • Added new MANIAL3 and MANIAL4 timing mode options for DPH1/2/3 in Table 7-2 • Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation 233 • Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation 233 • Updated Timing specification values for McASP2 in Table 7-56 • Updated Timing specification values for McASP2 in Table 7-56 • Updated Timing specification values for McASP2 in Table 7-56 • Updated Timing specification of McASP2 in Table 7-56 • Updated Timing specification of McASP2 in Table 7-56 • Updated Hynological diagnams (parameters HS2006 and HS2006) • Removed McASP "ahckx" signals from Table 7-64 to avoid confusion 300 • Updated Hynological diagnams (parameters HS2006 and HS2006) • Removed 114a / (cJTAG) support 300 • Added Romach Romach Romach Romach							
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Changes from November 28, 2016 to June 6, 2017 (from B Revision (November 2016) to C Revision)  - Moved device hex code from TRM to DM	TEXAS INSTRUMENTS			AM5728, A	AM5726		
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Device Family  AM5726, AM5728  SPRS953B  SPRS953C  These changes may be reviewed at the datasheet links provided.  http://www.ti.com/product/AM5726  Reason for Change:  To accurately reflect device characteristics.  Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):  No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.  Changes to product identification resulting from this PCN:	<ul> <li>Updated column description parameter [4] in Ball Characteristics Table.</li> <li>Added a note to gpmc_a[22:19] and gpmc_a[27:24] signals about internal pulldowns activation</li> <li>Changed GPMC 1 Load / 5 Load to Default Mode / Alternate Mode in Table 4-29</li> <li>Added footnotes in Electrical Characteristics section clarifying VDDS in each table</li> <li>Added RC On-die Oscillator Clock section</li> <li>Changed GPMC 1 Load / 5 Load names to Default Mode / Alternate Mode</li> <li>Changed GPMC 1 Load / 5 Load names to Default Mode / Alternate Mode</li> <li>Added new MANUAL3 and MANUAL4 timing mode options for DP11/2/3 in Table 7-2</li> <li>Added mmc3_clk row into the Manual Function Mapping for VIP1 2B table</li> <li>Added DSS clock jitter footnotes on Table 7-15 and Table 7-16</li> <li>Added New DSS Timing Specification Tables for Manual 3 and Manual 4 Mode Operation</li> <li>Updated Timing specification values for McASP2 in Table 7-56</li> <li>Updated Virtual Mode Case Details for McASP2 in Table 7-56</li> <li>Removed McASP "ahclkx" signals from Table 7-63 and Table 7-64 to avoid confusion</li> <li>Updated HS200 timing diagrams (parameters HS2005 and HS2006)</li> <li>Removed 1149.7 (cJTAG) support</li> <li>Updated PDN application report link and literature number</li> <li>Added references to thermal application notes</li> <li>Added section LJCB_REFN/P Connections</li> </ul>						
AM5726, AM5728  SPRS953B  SPRS953C  These changes may be reviewed at the datasheet links provided. <a href="http://www.ti.com/product/AM5726">http://www.ti.com/product/AM5726</a> Reason for Change:  To accurately reflect device characteristics.  Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):  No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.  Changes to product identification resulting from this PCN:		Change From:		Change To:			
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<b>Product Affected:</b>			
AM5726BABCX	AM5726BABCXA	AM5726BABCXAR	AM5726BABCXEA
AM5728BABCX	AM5728BABCXA	AM5728BABCXEA	XAM5728AABCXE
XAM5728BABCXE			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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